ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute									us Materia	als and Mf	g Inform	ation	
Supplier Info	rmation						·								
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2025-08-31			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Ste	ewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Ste	ewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Reque	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Versio	Version Manu		ufacturing Site		eight*	UOM	Unit Type
		NLSX5011MUTCG		1 BIT CONFIG TRANSLATOR		R	2025-08-31 THB			20.0		mg	Each		
Ianufacturin	ng Proccess Informatio	n						,							
Termin	d Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	TD-020 MSL Rating		Peak Process Body Temperatur		re Max Time at Peak Temper		Temperatu	rature Number of Reflow Cycles		eles
Precio Sn)			CU Alloy		1		260		С	30 seco		second	s 3		
Comments															
vel 1 - maximur	m time at peak temperature	during sol	ldering is 10-3	0 seconds											
or more inform	ation regarding material cor	nposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction that such information is true and correction to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	0.45	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.144	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.306	mg
Lead Frame	6.97	mg	Supplier	Tin (Sn)	7440-31-5		0.0174	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0153	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0174	mg
			Supplier	Copper (Cu)	7440-50-8		6.9198	mg
Mold Compound-Black	10.0	mg		Epoxy resin	proprietary data		0.7	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.5	mg
			Supplier	Carbon Black (C)	1333-86-4		0.05	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.05	mg
Plating	0.71	mg	Supplier	Palladium (Pd)	7440-05-3		0.0227	mg
			В	Nickel (Ni)	7440-02-0		0.6795	mg
			Supplier	Gold (Au)	7440-57-5		0.0078	mg
Wire Bond - Au	1.67	mg	Supplier	Gold (Au)	7440-57-5		1.67	mg